

**(19) World Intellectual Property  
Organization  
International Bureau**



**(43) International Publication Date**  
**27 January 2005 (27.01.2005)**

**PCT**

**(10) International Publication Number**  
**WO 2005/008743 A2**

**(51) International Patent Classification<sup>7</sup>: H01L 21/00**

**(21) International Application Number:** PCT/GB2004/002999

**(22) International Filing Date:** 9 July 2004 (09.07.2004)

(25) Filing Language: English

**(26) Publication Language:** English

**(30) Priority Data:**  
0316392.0                      12 July 2003 (12.07.2003)      GB

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**(81) Designated States (unless otherwise indicated, for every kind of national protection available):** AE, AG, AI., AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SI., SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

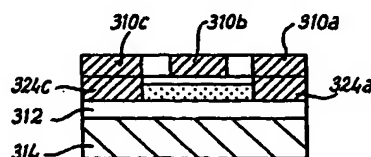
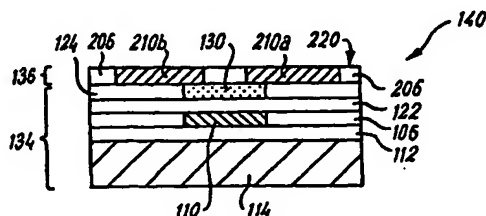
**(84) Designated States (unless otherwise indicated, for every kind of regional protection available):** ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**

- without international search report and to be republished upon receipt of that report

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

**(54) Title:** A SEMICONDUCTOR DEVICE WITH METALLIC ELECTRODES AND A METHOD FOR USE IN FORMING SUCH A DEVICE



**(57) Abstract:** A semiconductor device comprising: a first electrode component; a second electrode component; a first layer comprising at least a portion of the first electrode component and at least a portion of the second electrode component; a second layer having a portion comprising deposited semiconductor material contacting the first and second electrode components; and a third layer comprising a substrate, wherein the first, second and third layers are arranged in order such that the second layer is positioned between the first layer and the third layer and wherein the first and second electrode components comprise electro-deposited metal. A method for use in forming a layered semiconductor device comprising: forming a transfer layer on a conductive carrier by the deposition of insulating material on the conductive carrier and then the electro-deposition of metal onto at least first and second portions of the conductive carrier, selectively exposed through the insulating material, to form first and second metal portions; fixing the transfer layer to a substrate portion of the device; and removing the conductive carrier from the device.

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
27 January 2005 (27.01.2005)

PCT

(10) International Publication Number  
**WO 2005/008743 A3**

(51) International Patent Classification<sup>7</sup>: **H01L 51/40,**  
21/28

(21) International Application Number:  
PCT/GB2004/002999

(22) International Filing Date: 9 July 2004 (09.07.2004)

(25) Filing Language: English

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(30) Priority Data:  
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AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,  
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,  
GB, GD, GI, GL, GM, GR, GU, HN, ID, IL, IN, IS, JP, KE,  
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,  
MG, MK, MN, MW, MX, MY, NA, NI, NO, NZ, OM, PG,  
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,  
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ZW.

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SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,  
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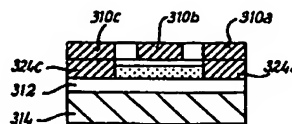
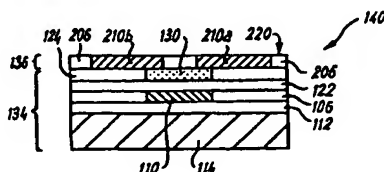
**Published:**

- with international search report
- before the expiration of the time limit for amending the  
claims and to be republished in the event of receipt of  
amendments

(88) Date of publication of the International search report:  
21 July 2005

For two-letter codes and other abbreviations, refer to the "Guid-  
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